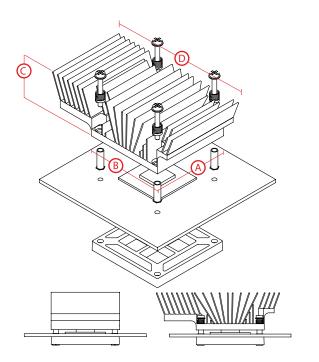


High Performance LGA Cooling Solutions

ATS PART # ATS-57001-C1-R0

Features & Benefits

- » Provides high capacity cooling for high power LGAs
- » Unique attachment minimizes mechanical stress on the device
- » Includes spring-loaded, push pin mounts for direct attachment to the PCB



*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	1.01	0.6	
300	1.5	0.81		
400	2.0	0.7		
500	2.5	0.62		
600	3.0	0.57		
700	3.5	0.52		
800	4.0	0.48		
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Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
56 mm	56 mm	31 mm	N/A mm	NO TIM	BLACK-ANODIZED

NOTES:

1) Dimension C = heat sink height from bottom of the base to the top of the fin field.

 Thermal performance data are provided for reference only. Actual performance may vary by application.

 ATS reserves the right to update or change its products without notice to improve the design or performance.

4) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

Thermal Performance